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(12) **United States Design Patent**
Horio

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(54) **RESIN-PACKAGED OPTICAL COMMUNICATION MODULE**
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(**) Term: **14 Years**
(21) Appl. No.: **29/253,462**
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(30) **Foreign Application Priority Data**
Aug. 17, 2005 (JP) 2005-023768
(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/165; D14/358**
(58) **Field of Classification Search** D14/240,
D14/339, 358, 256, 353, 299, 300; D13/184,
D13/123, 199, 101, 165; 379/433.01-433.13,
379/434, 419, 413.04; 220/4.02; 385/16-18,
385/92

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See application file for complete search history.

(57) **CLAIM**

The ornamental design for a resin-packaged optical communication module, as shown and described.

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DESCRIPTION

FIG. 1 is a front elevation of a resin-packaged optical communication module showing my new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a bottom plan view thereof;
FIG. 4 is a rear elevation thereof;
FIG. 5 is a left side elevation thereof;
FIG. 6 is a right side elevation thereof; and,
FIG. 7 is a cross-section thereof taken along line 7-7 in FIG. 2.

1 Claim, 2 Drawing Sheets



FIG.1

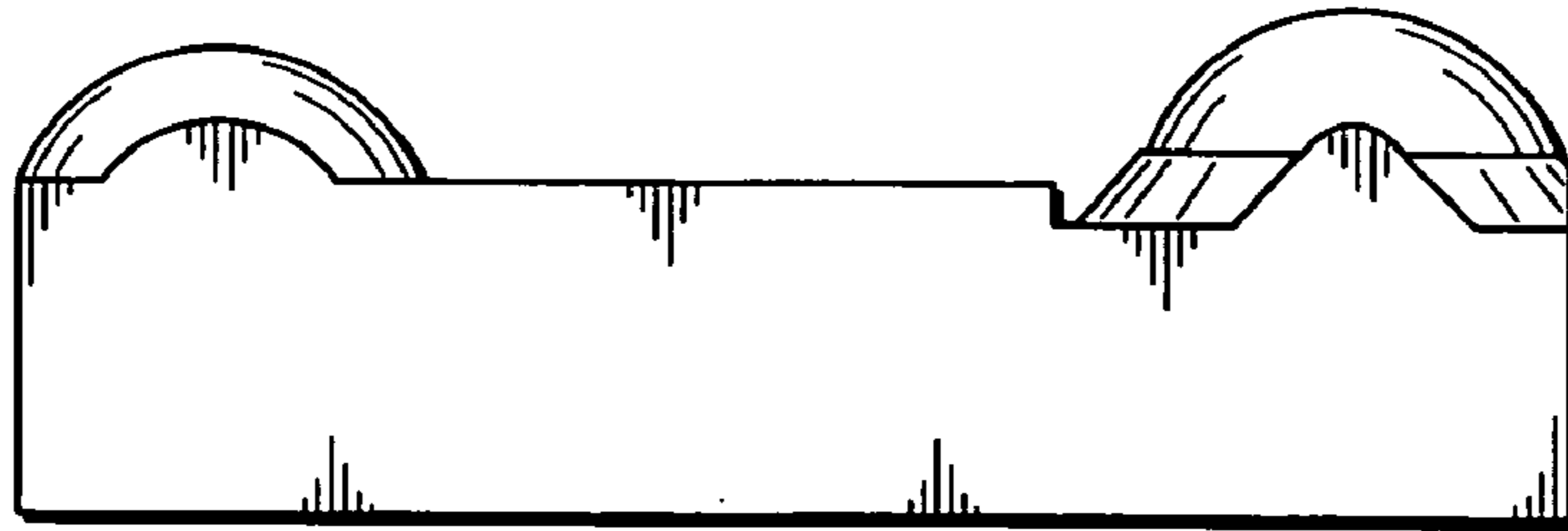


FIG.2

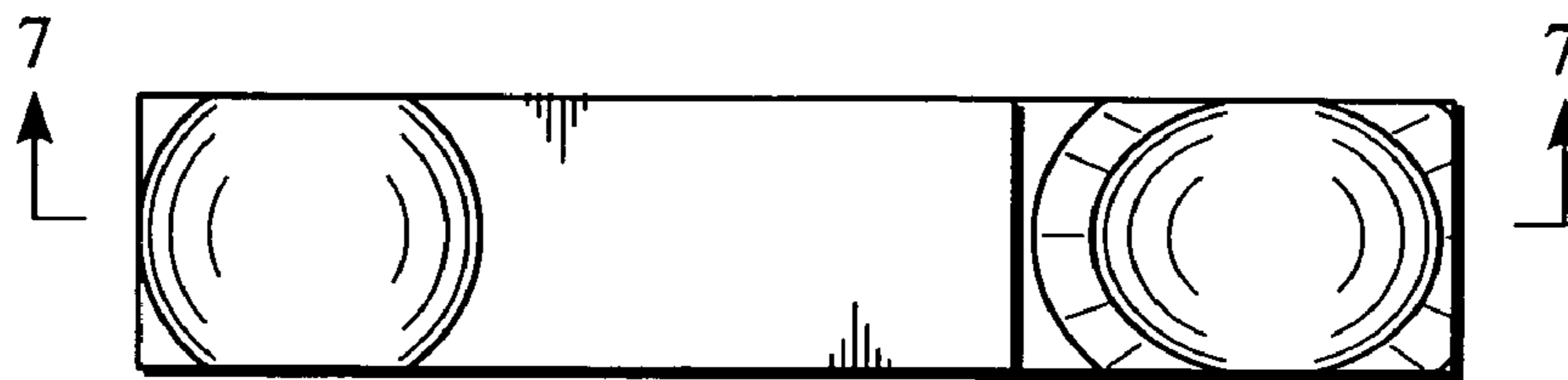


FIG.3

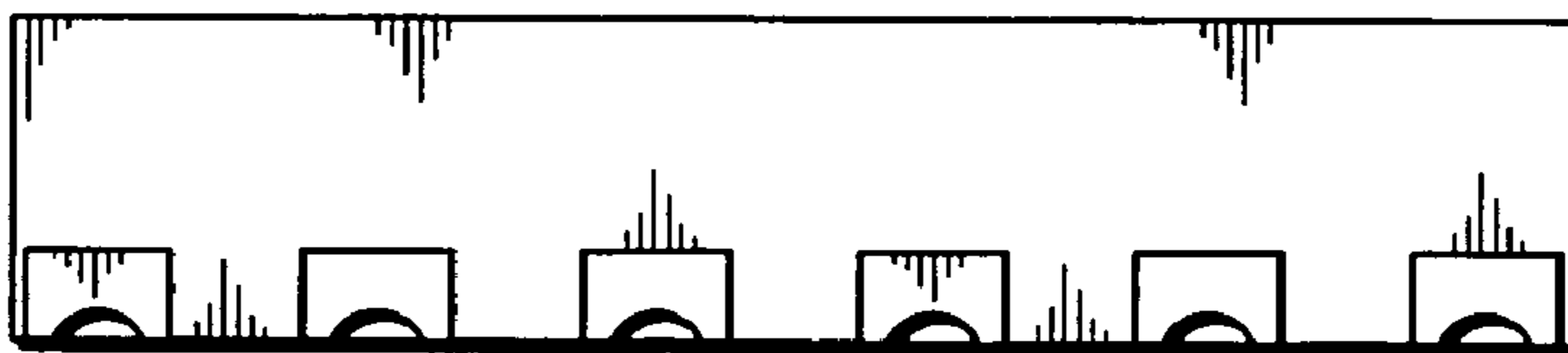


FIG.4



FIG.5

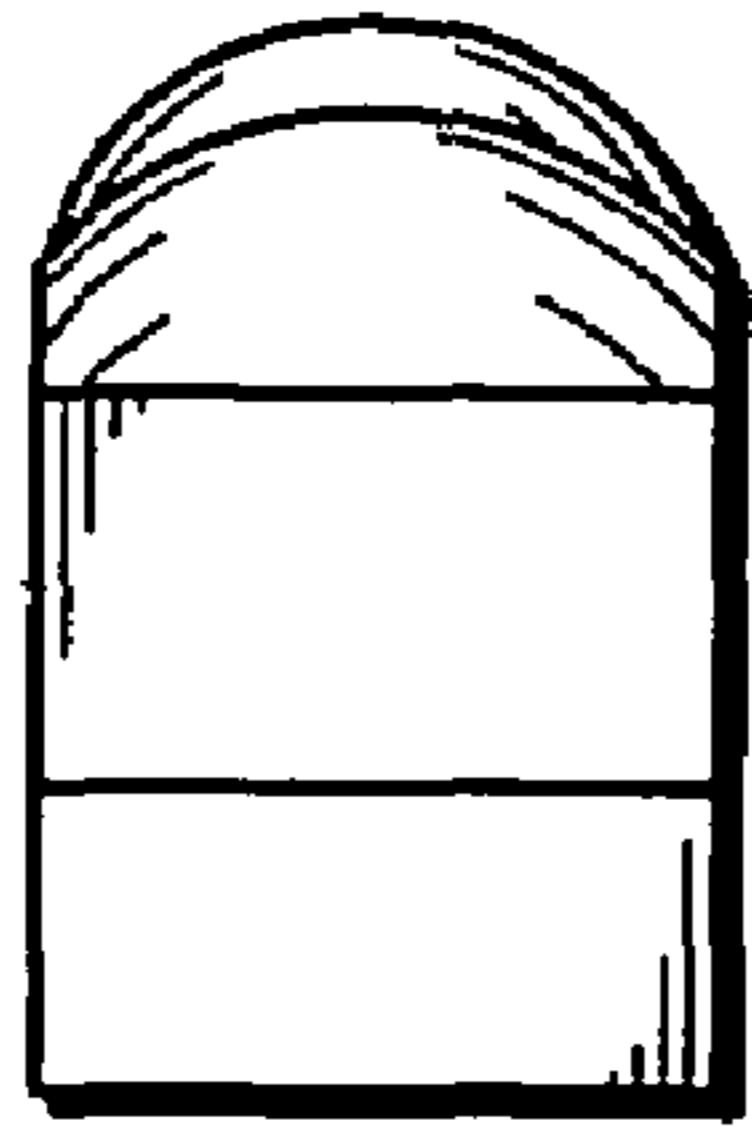


FIG.6

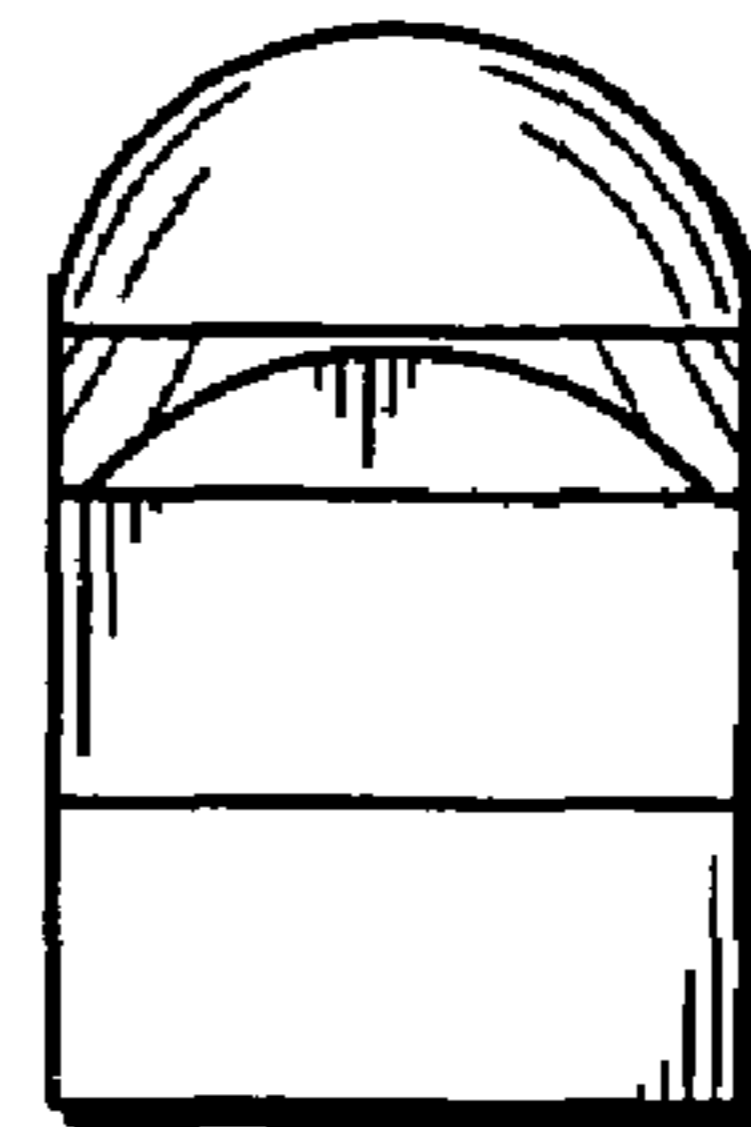


FIG.7

